AMENDMENTS TO THE CLAIMS

1. (Currently amended) An electronic circuit device comprising:

an electronic component having a connection terminal on one side thereof;

a circuit board made of a polymeric resin sheet having a thickness of from 50μm to 400μm and having an electrode pad thereon;

an adhesive sheet having a through-hole; and

a conductive adhesive filled in said through-hole,

wherein said electronic component and said circuit board are bonded to each other via said adhesive sheet, and said connection terminal on said electronic component and said electrode pad on said circuit board are bonded to each other by said conductive adhesive filled in said through-hole, and

wherein a cross-sectional size of said connection terminal is less than a corresponding cross-sectional size of said through-hole, and said corresponding cross-sectional size of said through-hole is less than a corresponding cross-sectional size of said electrode pad, with said corresponding cross-sectional size of said electrode pad being at least twice as large as said cross-sectional size of said connection terminal.

2. (Previously presented) The electronic circuit device according to claim 1, wherein said connection terminal protrudes into said through-hole.

3. (Canceled)

4. (Currently amended) The electronic circuit device according to claim 1, wherein said polymeric resin sheet is made of a material selected from the group consisting of polyethylene terephthalate, acrylnitrile-butadiene-styrene, and polycarbonate~~, and polyimide~~.

5. (Previously presented) The electronic circuit device according to claim 1, wherein said conductive adhesive is a conductive paste consisting essentially of conductive particles and a thermosetting resin binder.

6. (Previously presented) The electronic circuit device according to claim 1, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

7. (Previously presented) The electronic circuit device according to claim 1, wherein said conductive adhesive essentially consists of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

8. (Withdrawn) A method of manufacturing an electronic circuit device, comprising:

bonding an adhesive sheet to a circuit board so that a through-hole, through said adhesive sheet, is aligned with an electrode pad provided on a surface of said circuit board;

providing a conductive adhesive in said through-hole; and

bonding a connection terminal, provided on one side of an electronic component, to said electrode pad on said circuit board via said conductive adhesive in said through-hole, and bonding said electronic component to said adhesive sheet.

9. (Withdrawn) The method according to claim 8, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

10. (Withdrawn) The method according to claim 8, wherein said conductive adhesive consists essentially of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

11. (Canceled)

12. (Canceled)